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(54) **RADIO FREQUENCY MODULE**

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(57) **ABSTRACT**

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A radio frequency module includes a module substrate having main surfaces that are opposite to each other, a plurality of external connection terminals that are disposed on the main surface, a power amplifier circuit that is disposed on the main surface and supports a first power class, a power amplifier circuit that is disposed on the main surface and supports a second power class, a transformer that is connected to the power amplifier circuit and disposed on the main surface, and a transformer that is connected to the power amplifier circuit and disposed on the main surface. The second power class is defined by a maximum output power higher than a third power class. The first power class is defined by a maximum output power lower than the second power class or the same maximum output power as the second power class.

